

v00.0511



GaAs MMIC SMT SINGLE BALANCED MIXER, 1.7 - 3.0 GHz

Typical Applications

The HMC272AMS8 / HMC272AMS8E is ideal for:

- Up or Down Converter for PCS
- W-CDMA
- 2.4 GHz ISM
- MMDS

Features

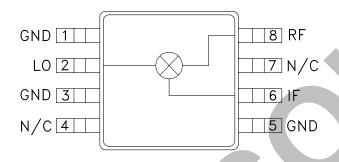
RoHS Compliant Product

Ultra Small Package: MSOP8

LO / RF Isolation: 32 dB

Input IP3: +20 dBm

Functional Diagram



General Description

The HMC272AMS8 & HMC272AMS8E are general purpose ultra miniature single balanced mixers in 8 lead plastic surface mount Mini Small Outline Packages (MSOP). This passive MMIC mixer is constructed of GaAs Schottky diodes and a novel planar transformer balun on the chip. The RF port is balanced via the MMIC balun while the LO port is connected directly to the diodes. The consistent MMIC performance will improve system operation and assure regulatory compliance.

Electrical Specifications, $T_A = +25^{\circ}$ C, As a Function of IF Frequency

Parameter	LO = +10 dBm IF = 100 MHz		LO = +10 dBm IF = 400 MHz			Units	
	Min.	Тур.	Max.	Min.	Тур.	Max.	
Frequency Range, RF & LO		2 - 3			1.7 - 2.8		GHz
Frequency Range, IF		DC - 0.8			DC - 0.8		GHz
Conversion Loss		9	10.5		9	11	dB
Noise Figure (SSB)		9	10.5		9	11	dB
LO to RF Isolation	22	30		24	32		dB
LO to IF Isolation	12	20		11	18		dB
IP3 (Input)	17	21		16	20		dBm
1 dB Compression (Input)	8	11		7	10		dBm

BALANCED MIXER, 1.7 - 3.0 GHz

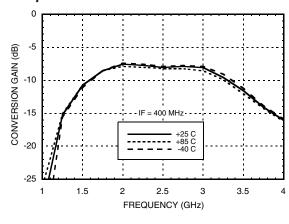
GaAs MMIC SMT SINGLE



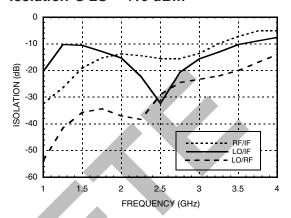
v00.0511



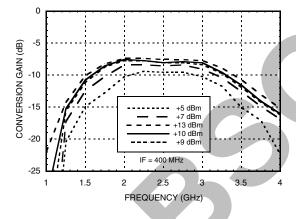
Conversion Gain vs. Temperature @ LO = +10 dBm



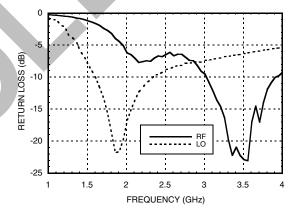
Isolation @ LO = +10 dBm



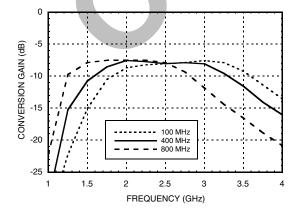
Conversion Gain vs. LO Drive



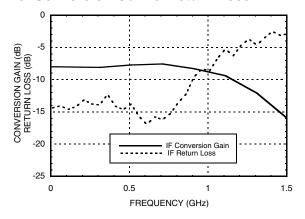
Return Loss @ LO = +10 dBm



Conversion Gain vs. IF Frequency



IF Bandwidth @ LO = +10 dBm vs. Conversion Gain & Return Loss



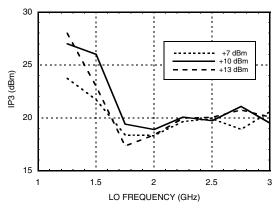


v02.0801

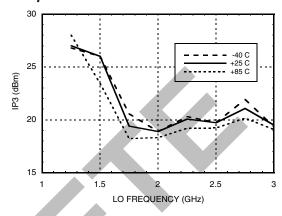


GaAs MMIC SMT SINGLE BALANCED MIXER, 1.7 - 3.0 GHz

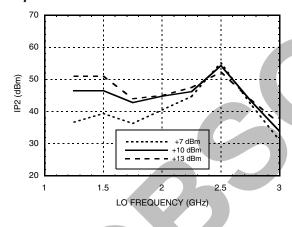
Input IP3 vs. LO Drive



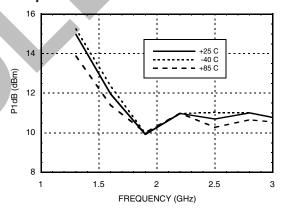
Input IP3 vs.
Temperature @ LO = +10 dBm



Input IP2 vs. LO Drive



P1dB vs.
Temperature @ LO = +10 dBm





v00.0511



GaAs MMIC SMT SINGLE BALANCED MIXER, 1.7 - 3.0 GHz

MxN Spurious Outputs

	nLO					
mRF	0	1	2	3	4	
0	xx	-11	-6	5	19	
1	7	0	37	27	38	
2	53	64	62	46	72	
3	83	>85	>85	>85	>85	
4	>85	>85	>85	>85	>85	

RF = 2.6 GHz @ -10 dBm LO = 2.2 GHz @ +13 dBm All values in dBc relative to the IF

Harmonics of LO

	nLO Spur at RF Port			
LO Frequency (GHz)	1	2	3	4
1.5	37	14	36	41
1.7	35	12	37	48
1.9	35	13	43	49
2.1	43	16	42	49
2.3	36	19	37	49
2.5	29	23	36	50

LO = +10 dBm Values in dBc below input LO level measured at the RF port.

Absolute Maximum Ratings

RF / IF Input	+13 dBm
LO Drive	+27 dBm
Storage Temperature	-65 to +150 °C
Operating Temperature	-40 to +85 °C
ESD Sensitivity (HBM)	Class 1A



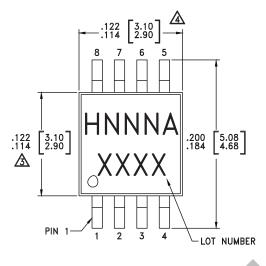
ELECTROSTATIC SENSITIVE DEVICE OBSERVE HANDLING PRECAUTIONS

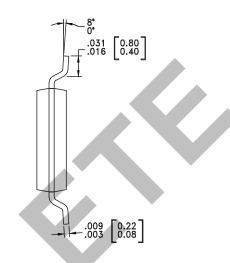
v00.0511

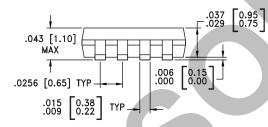


GaAs MMIC SMT SINGLE BALANCED MIXER, 1.7 - 3.0 GHz

Outline Drawing







NOTES

- 1. LEADFRAME MATERIAL: COPPER ALLOY
- 2. DIMENSIONS ARE IN INCHES [MILLIMETERS].
- DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.15mm PER SIDE.
- \triangle DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.25mm PER SIDE.
- 5. ALL GROUND LEADS MUST BE SOLDERED TO PCB RF GROUND.

Package Information

Part Number		Package Body Material	Lead Finish	MSL Rating	Package Marking [3]
HMC272AMS8		Low Stress Injection Molded Plastic	Sn/Pb Solder	MSL1 [1]	H272A XXXX
HMC272AMS8E	RoHS-	compliant Low Stress Injection Molded Plastic	100% matte Sn	MSL1 [2]	H272A XXXX

- [1] Max peak reflow temperature of 235 °C
- [2] Max peak reflow temperature of 260 $^{\circ}\text{C}$
- [3] 4-Digit lot number XXXX

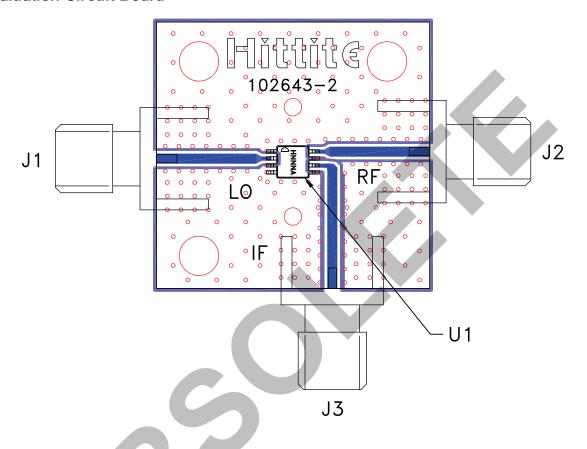


v00.0511



GaAs MMIC SMT SINGLE BALANCED MIXER, 1.7 - 3.0 GHz

Evaluation Circuit Board



List of Materials for Evaluation PCB 102781 [1]

Item	Description
J1 - J3	PCB Mount SMA RF Connector
U1	HMC272AMS8 / HMC272AMS8E Mixer
PCB [2]	102643 Evaluation Board

^[1] Reference this number when ordering complete evaluation PCB

The circuit board used in the application should use RF circuit design techniques. Signal lines should have 50 Ohm impedance while the package ground leads and exposed paddle should be connected directly to the ground plane similar to that shown. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation circuit board shown is available from Hittite upon request.

^[2] Circuit Board Material: Rogers 4350